

AST-1100 Automated Photoresist Bake Tool

A proven 300mm thermal process tool

Designed for 300mm wafer processing, the Despatch AST-1100 also accommodates 200mm wafers. This automated photoresist bake tool increases throughput and eliminates handling errors while conserving valuable floor space.

Product Features

Automation Features

- Accommodates both 200mm and 300mm wafers
- Semiconductor industry standard automation
 - Two Front Opening Unified Pod (FOUP) load port stations
 - Atmospheric Class 1 clean room compatible robot
 - Optically based Class 1 laser cassette mapping sensor
- Tool capacity: 50 wafers with standard two-chamber configuration. Additional chambers may be added.

Thermal Processing Features

- Inert atmosphere
- 175°C maximum temperature
- Temperature uniformity; +/-1.0°C at 95°C soak temperature
- Active cooling for quick cool down
- HEPA filters

Additional Features

- Complies with SEMI S2/S8 and SEMATECH appendices A, B, and C
- Graphical User Interface (GUI)
- Complies with 300mm SEMI communication standards
- FOUP ID reader

Options

- O₂ level monitoring
- Wafer ID reader
- Uninterruptible Power Supply (UPS)



Despatch

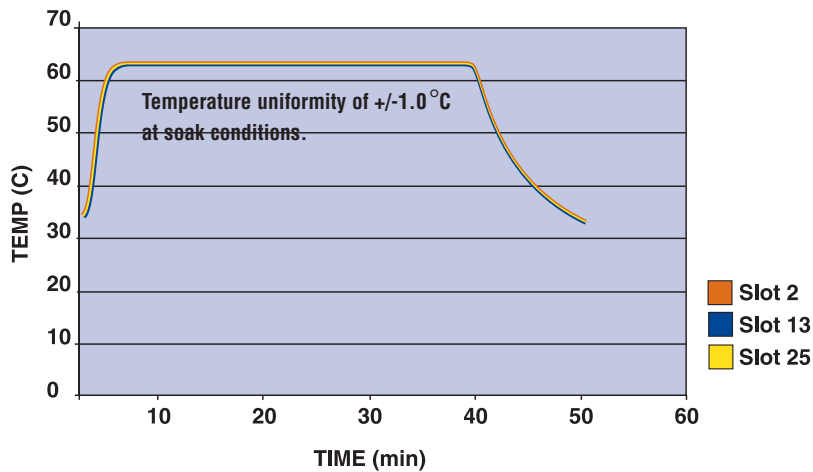
Increase Throughput, Eliminate Errors, and Improve Ergonomics.

Utilizing Despatch's automated wafer handling system will eliminate costly errors, improve ergonomics, and boost throughput. This process eliminates manual handling of 300mm wafers that exceed the weight limit for repetitive human handling, set by OSHA. The oven's two chambers each hold up to 25 wafers during the process cycle. Despatch can add additional heat chambers to increase throughput.

Conserve Valuable Clean Room Space.

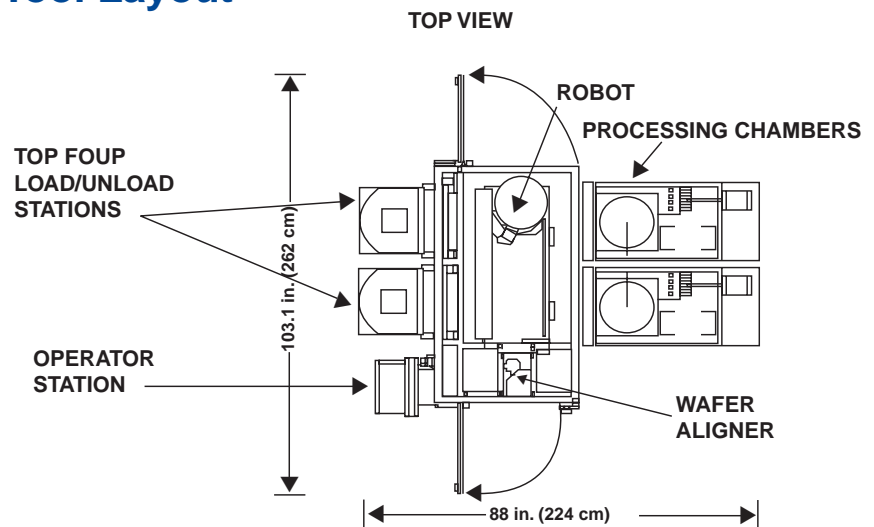
The Despatch 300mm oven measures approximately 103 inches (262 cm) wide by 88 inches (224 cm) long. Its small footprint will minimize clean room space needed and maximize your production environment. Compatible with either ballroom or bulkhead mounted installations.

Thermal Data



The Despatch AST-1100 Automated Photoresist Bake Tool provides tight temperature uniformity. The tool maintains uniformity of $\pm 1.0^{\circ}\text{C}$ within each wafer and throughout all 25 wafers in the thermal chamber at soak.

Tool Layout



where temperature is a technology

Despatch

Despatch Industries

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